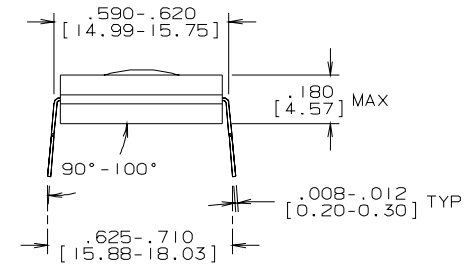
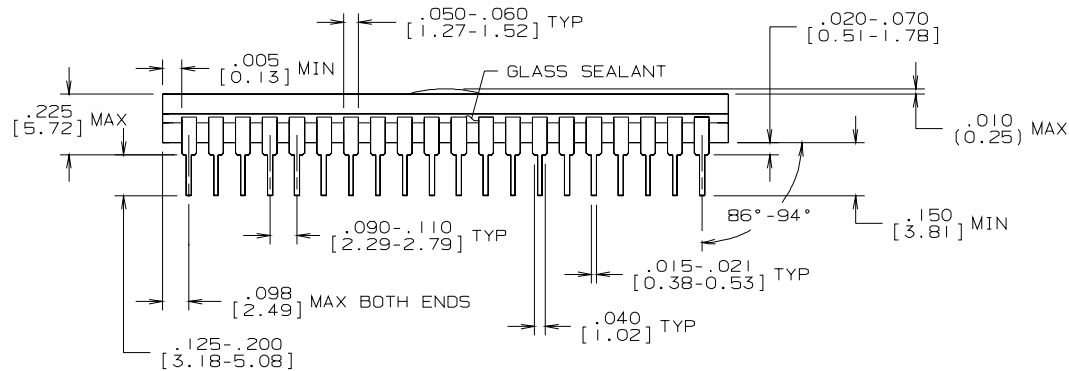
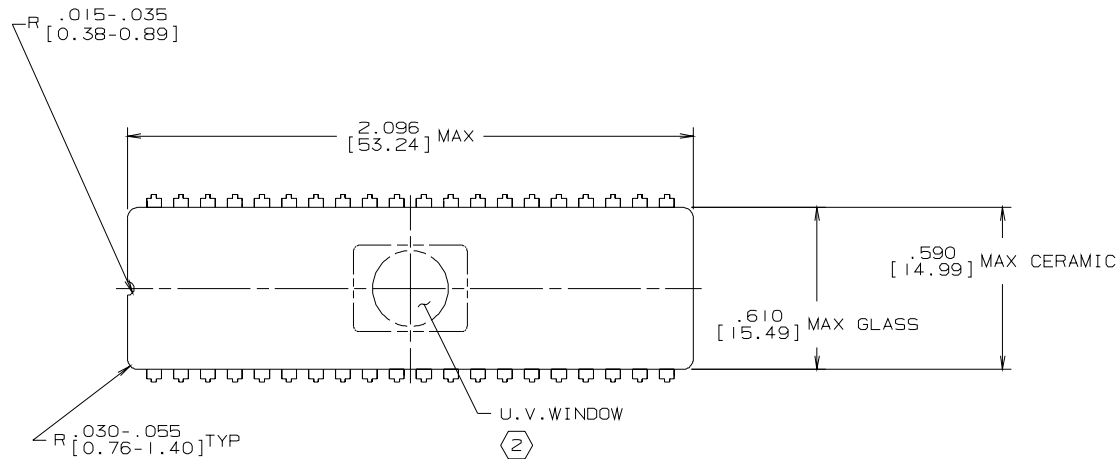


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	07842	10/13/90	PG/RC
B	DELETE UV WINDOW DIMS; ADD NOTE 2; UPDATE UV WINDOW.	08659	07/03/01	PG/



NOTES: UNLESS OTHERWISE SPECIFIED

1. LEAD FINISH TO BE ONE OF THE FOLLOWING:
  - a. 200 MICROINCHES/5.08 MICROMETERS MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
  - b. 200 TO 800 MICROINCHES/5.08 TO 20.32 MICROMETERS TIN PLATE OVER 50 TO 300 MICROINCHES/1.27 TO 7.62 MICROMETERS NICKEL UNDERPLATE OR BASIS METAL.
  - c. 50 TO 100 MICROINCHES/1.27 TO 2.54 MICROMETERS GOLD OVER 50 TO 350 MICROINCHES/1.27 TO 8.89 MICROMETERS NICKEL UNDERPLATE.

(2) UV WINDOW SIZE AND CONFIGURATION DETERMINED BY DEVICE SIZE.

APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION		
DRAWN PAMELA GIFFORD	4/13/90	2900 Semiconductor Drive, Santa Clara, CA 95052-8090		
DFTG. CHK.		CERDIP (JQ), 40 LEAD, EPROM		
ENGR. CHK.				
APPROVAL				
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
	N/A	C	MKT-J40BQ	B
	FORMERLY:	N/A	SHEET	OF